Silicon N-Channel MOS FET

HITACHI

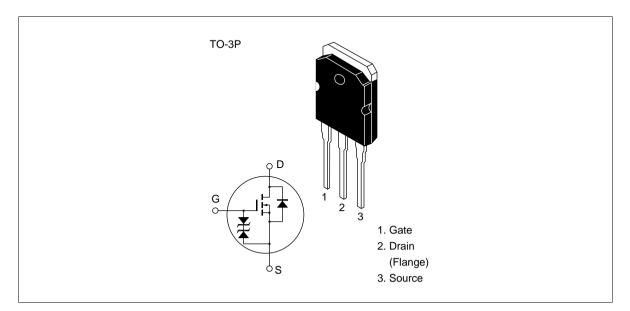
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator and DC-DC converter

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item		Symbol	Ratings	Unit
Drain to source voltage	2SK1161	V _{DSS}	450	V
	2SK1162		500	
Gate to source voltage		V _{GSS}	±30	V
Drain current		I _D	10	А
Drain peak current		I *1 D(pulse)	30	А
Body to drain diode reverse	e drain current	I _{DR}	10	A
Channel dissipation		Pch*2	100	W
Channel temperature		Tch	150	°C
Storage temperature	torage temperature Tstg		-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

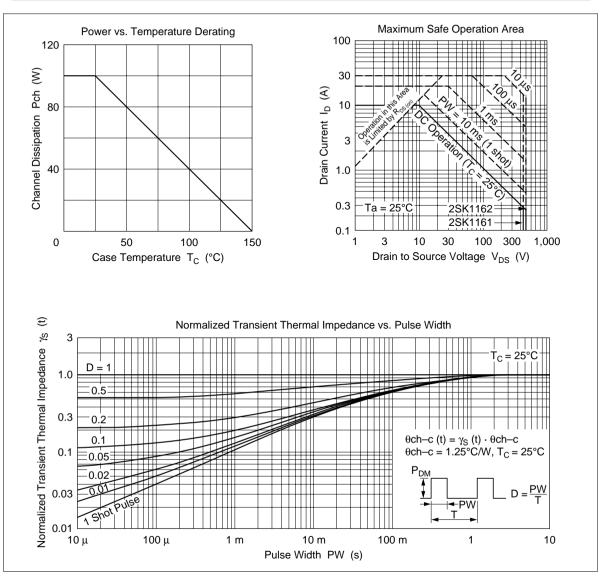
2. Value at $T_c = 25^{\circ}C$

Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source 2SK11	61 V _{(BR)DSS}	450		—	V	$I_{\rm D} = 10$ mA, $V_{\rm GS} = 0$
breakdown voltage 2SK11	62	500				
Gate to source breakdown voltage	$V_{(BR)GSS}$	±30	—	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage 2SK11	61 I _{DSS}	_	_	250	μΑ	$V_{\rm DS} = 360 \text{ V}, \text{ V}_{\rm GS} = 0$
drain current 2SK11	62					$V_{\rm DS} = 400 \text{ V}, \text{ V}_{\rm GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	2.0	_	3.0	V	$I_{\rm D} = 1 \text{ mA}, V_{\rm DS} = 10 \text{ V}$
Static Drain to source 2SK11	61 R _{DS(on)}	—	0.6	0.8	Ω	$I_{\rm D} = 5$ A, $V_{\rm GS} = 10$ V * ¹
on state resistance 2SK11	62	_	0.7	0.9	_	
Forward transfer admittance	yfs	4.0	7.0	—	S	$I_{\rm D} = 5$ A, $V_{\rm DS} = 10$ V * ¹
Input capacitance	Ciss	_	1050	_	pF	$V_{DS} = 10 V, V_{GS} = 0,$
Output capacitance	Coss	—	280	—	pF	f = 1 MHz
Reverse transfer capacitance	e Crss	_	40	—	pF	
Turn-on delay time	t _{d(on)}	_	15	_	ns	$I_{\rm D} = 5$ A, $V_{\rm GS} = 10$ V,
Rise time	t,	_	60	—	ns	$R_{L} = 6 \Omega$
Turn-off delay time	$t_{d(off)}$	_	90	—	ns	
Fall time	t _f	_	45	_	ns	
Body to drain diode forward voltage	V_{DF}	—	1.0	—	V	$I_{\rm F} = 10$ A, $V_{\rm GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	—	350	_	ns	$I_{F} = 10 \text{ A}, V_{GS} = 0,$ $di_{F}/dt = 100 \text{ A}/\mu\text{s}$

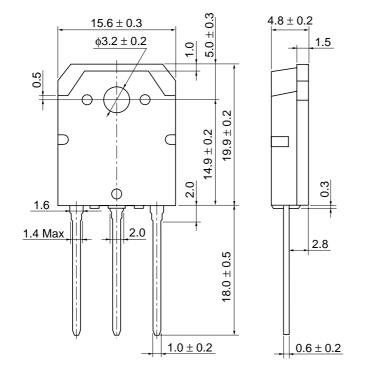
Note: 1. Pulse test

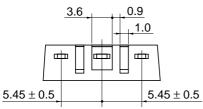
See characteristic curves of 2SK1157, 2SK1158.



Unit: mm

°O,





Hitachi Code	TO-3P
JEDEC	_
EIAJ	Conforms
Weight (reference value)	5.0 g

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